

Kindly enter the following amendments:

IN THE CLAIMS:

Please amend claim 1 as follows:

1. An RF package comprising:

a multilayered dielectric substrate on which first and second dielectric substrates are formed, said multilayered dielectric substrate having a cavity in the second dielectric substrate where a semiconductor element is to be mounted on the first dielectric substrate;

a feed-through for connecting an inside and outside of said cavity and comprised of a coplanar line formed on said first dielectric substrate and an inner layer line formed on the first dielectric substrate obtained by forming said second dielectric substrate on said coplanar line, said coplanar line and said inner layer line sharing a [strip-like] signal conductor formed on the first dielectric substrate; and

metal members formed at a connection interface between said coplanar line and said inner layer line on two sides of said signal conductor, and connecting ground conductors of the coplanar line and the inner layer line on the first dielectric substrate to a top surface of the second dielectric substrate at an edge of the second dielectric.